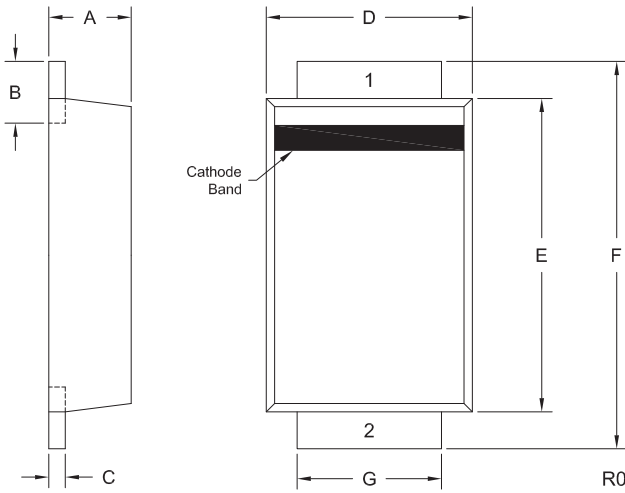


Package Details

SMAFL Case



Mechanical Drawing



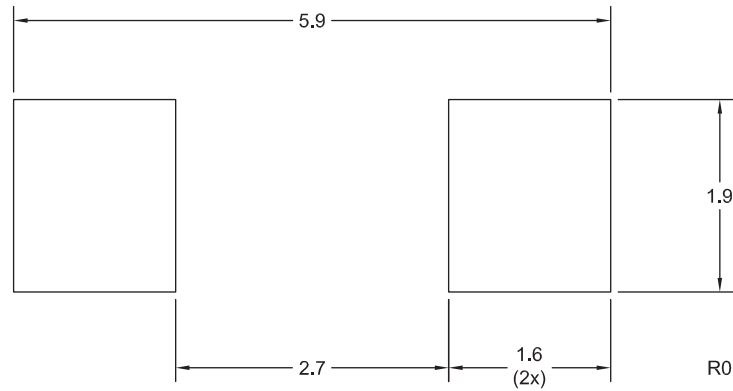
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.035	0.044	0.90	1.10
B	0.021	0.038	0.55	0.95
C	0.006	0.010	0.15	0.25
D	0.094	0.103	2.40	2.60
E	0.145	0.154	3.70	3.90
F	0.177	0.193	4.50	4.90
G	0.065	0.073	1.65	1.85

SMAFL (REV: R0)

Lead Code:
Reference individual device datasheet.

Part Marking: 3-6 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



R0 (27-March 2013)

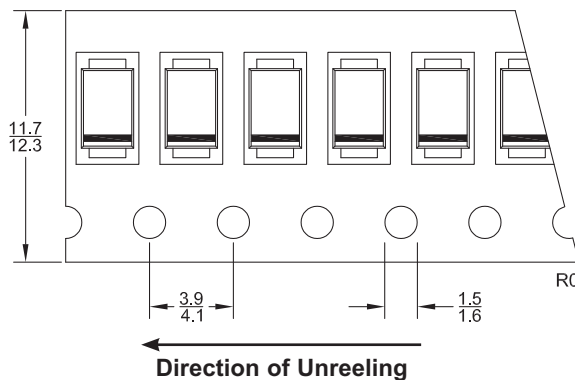
Package Details

SMAFL Case



Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 12mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

13" Reel = 10,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	5	50,000	15x4x15	38x10x38	10	5
	14	140,000	15x15x9	38x38x23	26	12
	26	260,000	15x15x18	38x38x46	47	22

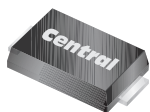
Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (27-March 2013)

Material Composition Specification

SMAFL Case



Device average mass **32.5 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.37%	0.77	Si	7440-21-3	2.37%	0.77	23,692
leadframe	copper alloy	53.4%	17.355	Cu	7440-50-8	53.32%	17.33	533,231
				Fe	7439-89-6	0.08%	0.025	769
die attach	high temperature solder paste	6.46%	2.1	Pb	7439-92-1	6.0%	1.95	60,000
				Sn	7440-31-5	0.29%	0.095	2,923
				Ag	7440-22-4	0.17%	0.055	1,692
encapsulation*	EMC GREEN	36.52%	11.87	silica (fused)	60676-86-0	28.15%	9.15	281,538
				epoxy resin	29690-82-2	3.63%	1.18	36,308
				phenol resin	9003-35-4	3.54%	1.15	35,385
				carbon black	1333-86-4	0.11%	0.035	1,077
				metal hydroxide	1309-42-8	1.09%	0.355	10,923
plating	matte tin	1.25%	0.405	Sn	7440-31-5	1.25%	0.405	12,462

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (13-August 2012)